

**ABSTRACT OF THE DISCLOSURE**

**ALTERNATIVE FLIP CHIP IN LEADED MOLDED PACKAGE DESIGN  
AND METHOD FOR MANUFACTURE**

A semiconductor package is disclosed. The package includes a leadframe structure comprising a die attach region and plurality of leads. A molding material is molded around at least a portion of the leadframe structure, and comprises a window. A semiconductor die comprising an edge is mounted on the die attach region and is within the window. A gap is present between the edge of the semiconductor die and the molding material.

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